



Sym	N°	Mils	MM	Qty	Plated
+	1	12	0.30	255	YES
×	2	20	0.50	2	YES
□	3	22	0.55	2	NOT
◇	4	40	1.02	56	YES
×	5	126	3.20	2	NOT

Class	RF	Type	Coated Coplanar Waveguide With Ground 1B		
TOP	Impedance	Trace Width		Trace Separation	Ground Separation
BOTTOM	50 Ohms	26 mils		N/A	6 mils
Class	USB	Type	Diff Coated Coplanar Waveguide With Ground 1B		
TOP	Impedance	Trace Width		Trace Separation	Ground Separation
BOTTOM	90 Ohms	14.5 mils		6 mils	6 mils
Class	Ethernet	Type	Diff Coated Coplanar Waveguide With Ground 1B		
TOP	Impedance	Trace Width		Trace Separation	Ground Separation
BOTTOM	100 Ohms	10 mils		6 mils	6 mils

1.061 MM \pm 10%

LAYER 4 LT16 TOP

18 UM CU + 12.5 UM PLATING (30.5 UM)

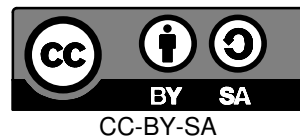
CORE

1.0 MM CORE FR-4 LG 135 INCLUDING COPPER

LAYER 4 LT16 BOTTOM

18 UM CU + 12.5 UM PLATING (30.5 UM)

1. PRINTED CIRCUIT BOARD MADE FROM NEMA GRADE FR-4 TO 135 EPOXY LAMINATE WITH 18 UM COPPER PLATING AND 1 MM THICKNESS.
2. ALL DIMENSIONS ARE GIVEN IN MILLIMETERS EXCEPT TRACE WIDTH/SPACE.
3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE WHITE SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY.
EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSREEN BOARD USING BLACK INK. DISTORTION OF SILKSREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
 - * 2 COPPER LAYERS
 - * 1 MM BOARD THICKNESS
 - * REQUIRES TOP AND BOTTOM SIDE SILKSREENS



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Solder side (.SOL)

Rev. B